

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination	
		09/682,347	LESLIE ET AL.	
Examiner		Art Unit		Page 1 of 1
Hugh Jones		2128		

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
A	US-	6,694,355	2-2004	Bahar	709/217
B	US-				
C	US-				
D	US-				
E	US-				
F	US-				
G	US-				
H	US-				
I	US-				
J	US-				
K	US-				
L	US-				
M	US-				

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
N						
O						
P						
Q						
R						
S						
T						

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Lee et al. "Application of a CFD tool for system level thermal simulation" IEEE Trans. Components pp. 564-572; 12/1994.
	W	An investigation of thermal enhancement Lee in flip chip BGA packages using CFD tool; IEEE Trans. Components; pp. 481-489; 9/2000.
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP §707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.